



#18/E(NE)  
5/19/3  
PATENT Surles  
Surles  
6/20/3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/829,161

Filed: April 9, 2001

For: METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME

Confirmation No.: 8260

Examiner: H. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 2269-3442.1US  
(96-0428.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

5/13/2003  
Date

Signature

Joseph A. Walkowski  
Name (Type/Print)

RECEIVED  
MAY 16 2003  
TECHNOLOGY CENTER 2900

AMENDMENT UNDER 37 C.F.R. §1.116

Mail Stop AF  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed March 21, 2003, the three-month shortened statutory period for

**Serial No. 09/829,161**

response to which expires on June 21, 2003. This response is submitted on or before two months from the mailing date of the Final Office Action.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 14 of this paper.